

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kenji SASAOKA	05/07/2010
RECEIVING PARTY DATA	
Name:	DAI NIPPON PRINTING CO., LTD.
Street Address:	1-1, Kaga-cho 1-chome, Ichigaya, Shinjuku-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	162-8001
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12740694
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ATTORNEY DOCKET NUMBER:	04173.0605-00000
NAME OF SUBMITTER:	Ann Denikos
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

OP \$40.00 12740694

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PATENT
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JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS, We, the below named inventors, (hereinafter referred to as assignors, have made an invention entitled:

COMPONENT BUILT-IN WIRING BOARD AND MANUFACTURING METHOD OF COMPONENT
BUILT-IN WIRING BOARD

for which we executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on 30/April/2010 (Application No. 12/740,694); and

WHEREAS, DAI NIPPON PRINTING CO., LTD., a corporation of Japan, whose post office address is _____

1-1, Kaga-cho 1-chome, Ichigaya, Shinjuku-ku, Tokyo 162-8001 Japan

(hereinafter referred to as assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, we, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY further covenant and agree that we will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, we have hereunto set our hands.

First Assignor

Name: Kenji SASAOKA
Address: Shinjuku-ku, Tokyo, Japan

Citizenship: Japan

Signature: Kenji Sasaka

Date: May 7, 2010

Second Assignor

Name: _____
Address: _____

Citizenship: _____

Signature: _____

Date: _____

Third Assignor

Name: _____
Address: _____

Citizenship: _____

Signature: _____

Date: _____